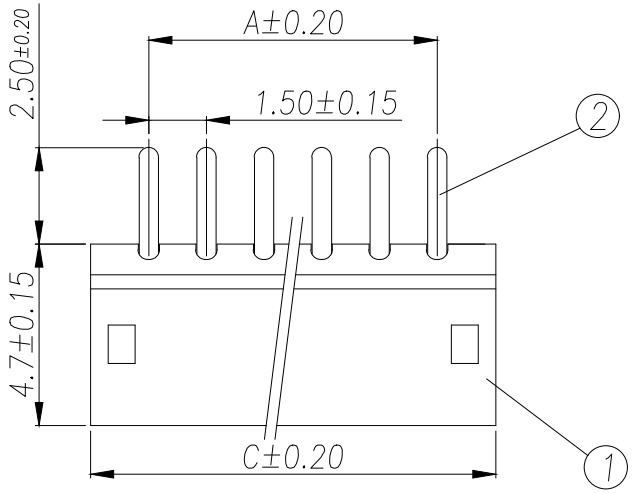
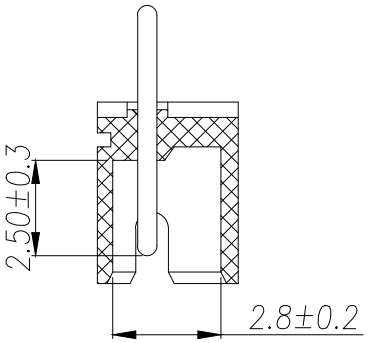
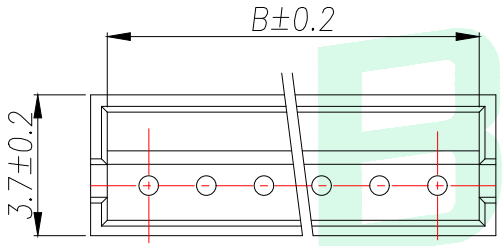
REV.	DESCRIPTION	ECN NO.	NAME	DATE





PRELIMINARY
DESIGN IS SUBJECT TO CHANGE WITHOUT PRIOR NOTICE

Part No	PIN	DIMA	DIMB	DIMC
WF-ZH1.5-2PZZ	2	1.5	3.6	4.5
WF-ZH1.5-3PZZ	3	3	5.1	6
WF-ZH1.5-4PZZ	4	4.5	6.6	7.5
WF-ZH1.5-5PZZ	5	6	8.1	9
WF-ZH1.5-6PZZ	6	7.5	9.6	10.5
WF-ZH1.5-7PZZ	7	9	11.1	12
WF-ZH1.5-8PZZ	8	10.5	12.6	13.5
WF-ZH1.5-9PZZ	9	12	14.1	15
WF-ZH1.5-10PZZ	10	13.5	15.6	16.5
WF-ZH1.5-11PZZ	11	15	17.1	18
WF-ZH1.5-12PZZ	12	16.5	18.6	19.5
WF-ZH1.5-13PZZ	13	18	20.1	21
WF-ZH1.5-14PZZ	14	19.5	21.6	22.5
WF-ZH1.5-15PZZ	15	21	23.1	24
WF-ZH1.5-16PZZ	16	22.5	24.6	25.5



ROHS管理规定:

1、禁止使用含有ROHS指令所限制的物质。

2、对应的SGS或ITS出具的ICP-AES数据、不可测定物质的成分表，有效期一年。

技术指标:

1、塑件表面应光洁、无毛刺、明显收缩、缺陷、裂纹等现象;

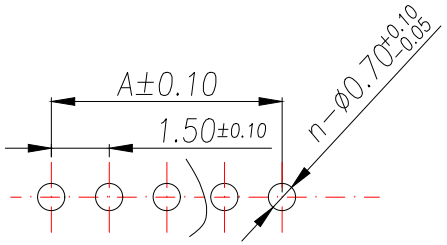
2、温度范围: -25°C~85°C;

3、额定电压: 250V, AC, DC(等效);

4、接触电阻: ≤0.03Ω;

5、绝缘电阻: ≥1000MΩ;

6、耐压: 1000V, AC/minute.



PCB寸法
PCB Layout

序号	名 称	材 料	数 量	附 注
2	Contact	Brass	n*1	电镀(锡): 整个表面镀底镍30u"MIN,再镀锡80u".MIN.
1	Wafer	PA66(UL94V-0)	1	白色

GENERAL TOLERANCE

DIM.	TOL.
X	
X.X	±0.30
X.XX	±0.25
X.XXX	±0.15
GENERAL ANGLE:	±3°

DONGGUAN BAOXUN PRECISION TECHNOLOGY CO., LTD

BXCONN®

TITLE: WAFER 1.5mm H3.7mm 180°DIP

DWG. NO.: WF-ZH1.5-XPZZ

DRAWN: MAX

PART NO.: WF-ZH1.5-XPZZ

CHECKED: ELLA

UNIT:	SCALE:	SHEET:	DWG. SIZE:	LAYER:
mm	none	1of 1	A4	bxconn

APPROVED: WILL